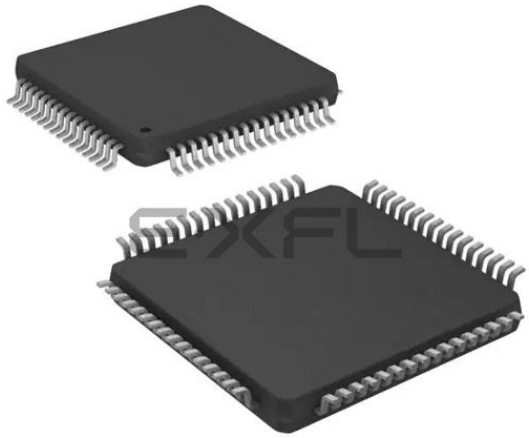


Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	dsPIC
Core Size	16-Bit
Speed	60 MIPs
Connectivity	I²C, IrDA, LINbus, QEI, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	53
Program Memory Size	512KB (170K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	24K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 16x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	64-TQFP
Supplier Device Package	64-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ep512mc206t-e-pt

TABLE 4-5: INTERRUPT CONTROLLER REGISTER MAP FOR dsPIC33EPXXXGP50X DEVICES ONLY (CONTINUED)

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
INTCON1	08C0	NSTDIS	OVAERR	OVBERR	COVAERR	COVBERR	OVATE	OVBTE	COVTE	SFTACERR	DIV0ERR	DMACERR	MATHERR	ADDRERR	STKERR	OSCFAIL	—	0000
INTCON2	08C2	GIE	DISI	SWTRAP	—	—	—	—	—	—	—	—	—	—	INT2EP	INT1EP	INT0EP	8000
INTCON3	08C4	—	—	—	—	—	—	—	—	—	—	DAE	DOOVR	—	—	—	—	0000
INTCON4	08C6	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	SGHT	0000
INTTREG	08C8	—	—	—	—	ILR<3:0>				VECNUM<7:0>								0000

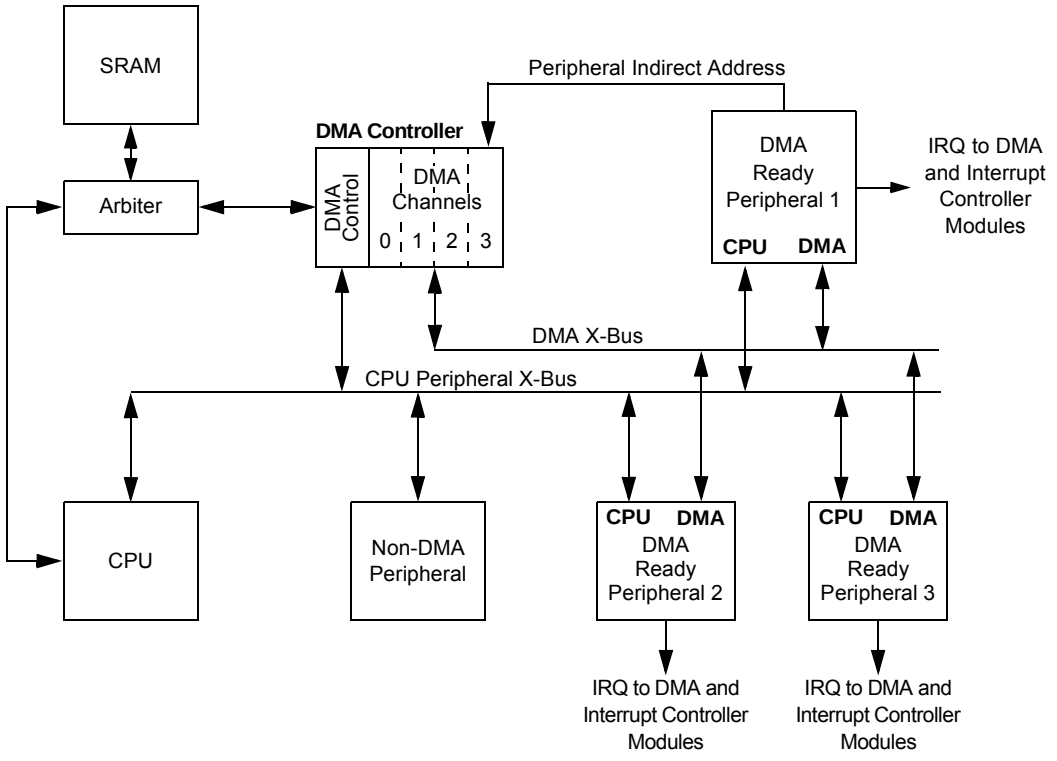
Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-6: INTERRUPT CONTROLLER REGISTER MAP FOR dsPIC33EPXXXMC20X DEVICES ONLY (CONTINUED)

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
IPC35	0886	—	JTAGIP<2:0>			—	ICDIP<2:0>			—	—	—	—	—	—	—	—	4400
IPC36	0888	—	PTG0IP<2:0>			—	PTGWDTIP<2:0>			—	PTGSTEPIP<2:0>			—	—	—	—	4440
IPC37	088A	—	—	—	—	—	PTG3IP<2:0>			—	PTG2IP<2:0>			—	PTG1IP<2:0>			0444
INTCON1	08C0	NSTDIS	OVAERR	OVBERR	COVAERR	COVBERR	OVATE	OVBTE	COVTE	SFTACERR	DIV0ERR	DMACERR	MATHERR	ADDRERR	STKERR	OSCFAIL	—	0000
INTCON2	08C2	GIE	DISI	SWTRAP	—	—	—	—	—	—	—	—	—	—	INT2EP	INT1EP	INT0EP	8000
INTCON3	08C4	—	—	—	—	—	—	—	—	—	—	DAE	DOOVR	—	—	—	—	0000
INTCON4	08C6	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	SGHT	0000
INTTREG	08C8	—	—	—	—	ILR<3:0>				VECNUM<7:0>								0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

FIGURE 8-2: DMA CONTROLLER BLOCK DIAGRAM



Note: CPU and DMA address buses are not shown for clarity.

8.1 DMA Resources

Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note:	In the event you are not able to access the product page using the link above, enter this URL in your browser: http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en555464

8.1.1 KEY RESOURCES

- **Section 22. "Direct Memory Access (DMA)"** (DS70348) in the "dsPIC33/PIC24 Family Reference Manual"
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All Related "dsPIC33/PIC24 Family Reference Manual" Sections
- Development Tools

8.2 DMAC Registers

Each DMAC Channel x (where x = 0 through 3) contains the following registers:

- 16-Bit DMA Channel Control register (DMAxCON)
- 16-Bit DMA Channel IRQ Select register (DMAxREQ)
- 32-Bit DMA RAM Primary Start Address register (DMAxSTA)
- 32-Bit DMA RAM Secondary Start Address register (DMAxSTB)
- 16-Bit DMA Peripheral Address register (DMAxPAD)
- 14-Bit DMA Transfer Count register (DMAxCNT)

Additional status registers (DMAPWC, DMARQC, DMAPPS, DMALCA and DSADR) are common to all DMAC channels. These status registers provide information on write and request collisions, as well as on last address and channel access information.

The interrupt flags (DMAxIF) are located in an IFSx register in the interrupt controller. The corresponding interrupt enable control bits (DMAxIE) are located in an IECx register in the interrupt controller, and the corresponding interrupt priority control bits (DMAxIP) are located in an IPCx register in the interrupt controller.

REGISTER 11-8: RPINR14: PERIPHERAL PIN SELECT INPUT REGISTER 14 (dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X DEVICES ONLY)

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	QEB1R<6:0>						
bit 15							bit 8

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	QEA1R<6:0>						
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as ‘0’

bit 14-8 **QEB1R<6:0>:** Assign B (QEB) to the Corresponding RPn Pin bits (see Table 11-2 for input pin selection numbers)

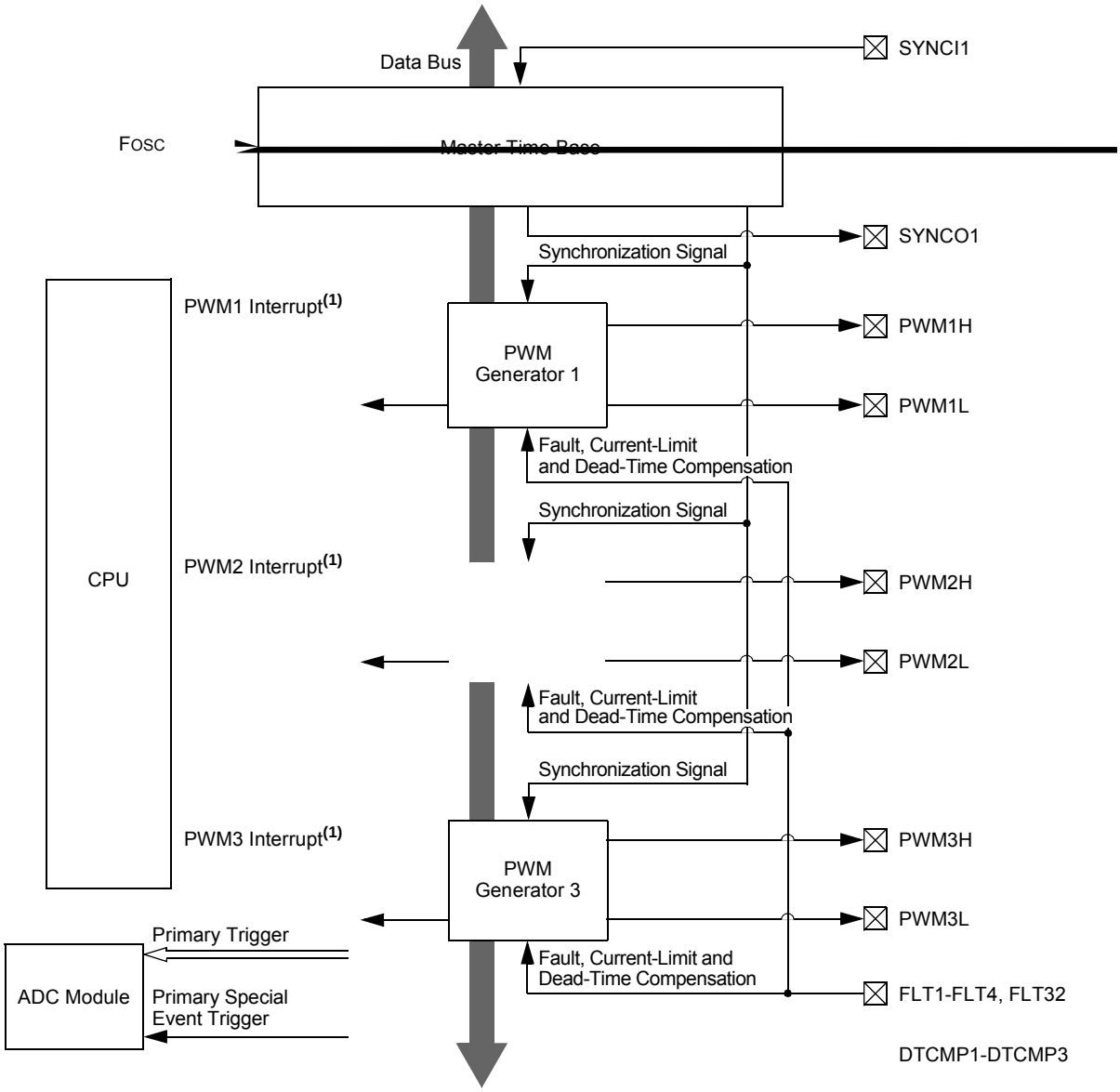
1111001 = Input tied to RPI121
.
.
.
0000001 = Input tied to CMP1
0000000 = Input tied to Vss

bit 7 **Unimplemented:** Read as ‘0’

bit 6-0 **QEA1R<6:0>:** Assign A (QEA) to the Corresponding RPn Pin bits (see Table 11-2 for input pin selection numbers)

1111001 = Input tied to RPI121
.
.
.
0000001 = Input tied to CMP1
0000000 = Input tied to Vss

FIGURE 16-1: HIGH-SPEED PWMx MODULE ARCHITECTURAL OVERVIEW



REGISTER 16-16: LEBCONx: PWMx LEADING-EDGE BLANKING CONTROL REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	U-0
PHR	PHF	PLR	PLF	FLTLEBEN	CLLEBEN	—	—
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	BCH(1)	BCL(1)	BPHH	BPHL	BPLH	BPLL
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **PHR:** PWMxH Rising Edge Trigger Enable bit
1 = Rising edge of PWMxH will trigger Leading-Edge Blanking counter
0 = Leading-Edge Blanking ignores rising edge of PWMxH

bit 14 **PHF:** PWMxH Falling Edge Trigger Enable bit
1 = Falling edge of PWMxH will trigger Leading-Edge Blanking counter
0 = Leading-Edge Blanking ignores falling edge of PWMxH

bit 13 **PLR:** PWMxL Rising Edge Trigger Enable bit
1 = Rising edge of PWMxL will trigger Leading-Edge Blanking counter
0 = Leading-Edge Blanking ignores rising edge of PWMxL

bit 12 **PLF:** PWMxL Falling Edge Trigger Enable bit
1 = Falling edge of PWMxL will trigger Leading-Edge Blanking counter
0 = Leading-Edge Blanking ignores falling edge of PWMxL

bit 11 **FLTLEBEN:** Fault Input Leading-Edge Blanking Enable bit
1 = Leading-Edge Blanking is applied to selected Fault input
0 = Leading-Edge Blanking is not applied to selected Fault input

bit 10 **CLLEBEN:** Current-Limit Leading-Edge Blanking Enable bit
1 = Leading-Edge Blanking is applied to selected current-limit input
0 = Leading-Edge Blanking is not applied to selected current-limit input

bit 9-6 **Unimplemented:** Read as '0'

bit 5 **BCH:** Blanking in Selected Blanking Signal High Enable bit(1)
1 = State blanking (of current-limit and/or Fault input signals) when selected blanking signal is high
0 = No blanking when selected blanking signal is high

bit 4 **BCL:** Blanking in Selected Blanking Signal Low Enable bit(1)
1 = State blanking (of current-limit and/or Fault input signals) when selected blanking signal is low
0 = No blanking when selected blanking signal is low

bit 3 **BPHH:** Blanking in PWMxH High Enable bit
1 = State blanking (of current-limit and/or Fault input signals) when PWMxH output is high
0 = No blanking when PWMxH output is high

bit 2 **BPHL:** Blanking in PWMxH Low Enable bit
1 = State blanking (of current-limit and/or Fault input signals) when PWMxH output is low
0 = No blanking when PWMxH output is low

bit 1 **BPLH:** Blanking in PWMxL High Enable bit
1 = State blanking (of current-limit and/or Fault input signals) when PWMxL output is high
0 = No blanking when PWMxL output is high

bit 0 **BPLL:** Blanking in PWMxL Low Enable bit
1 = State blanking (of current-limit and/or Fault input signals) when PWMxL output is low
0 = No blanking when PWMxL output is low

Note 1: The blanking signal is selected via the BLANKSELx bits in the AUXCONx register.

REGISTER 17-13: QEI1LECH: QEI1 LESS THAN OR EQUAL COMPARE HIGH WORD REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
QEILEC<31:24>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
QEILEC<23:16>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-0 **QEILEC<31:16>:** High Word Used to Form 32-Bit Less Than or Equal Compare Register (QEI1LEC) bits

REGISTER 17-14: QEI1LECL: QEI1 LESS THAN OR EQUAL COMPARE LOW WORD REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
QEILEC<15:8>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
QEILEC<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-0 **QEILEC<15:0>:** Low Word Used to Form 32-Bit Less Than or Equal Compare Register (QEI1LEC) bits

18.0 SERIAL PERIPHERAL INTERFACE (SPI)

Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Serial Peripheral Interface (SPI)"** (DS70569) in the "dsPIC33/PIC24 Family Reference Manual", which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The SPI module is a synchronous serial interface, useful for communicating with other peripheral or microcontroller devices. These peripheral devices can be serial EEPROMs, shift registers, display drivers, ADC Converters, etc. The SPI module is compatible with Motorola® SPI and SIOP interfaces.

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X device family offers two SPI modules on a single device. These modules, which are designated as SPI1 and SPI2, are functionally identical. Each SPI module includes an eight-word FIFO buffer and allows DMA bus connections. When using the SPI module with DMA, FIFO operation can be disabled.

Note: In this section, the SPI modules are referred to together as SPIx, or separately as SPI1 and SPI2. Special Function Registers follow a similar notation. For example, SPIxCON refers to the control register for the SPI1 and SPI2 modules.

The SPI1 module uses dedicated pins which allow for a higher speed when using SPI1. The SPI2 module takes advantage of the Peripheral Pin Select (PPS) feature to allow for greater flexibility in pin configuration of the SPI2 module, but results in a lower maximum speed for SPI2. See **Section 30.0 "Electrical Characteristics"** for more information.

The SPIx serial interface consists of four pins, as follows:

- SDIx: Serial Data Input
- SDOx: Serial Data Output
- SCKx: Shift Clock Input or Output
- $\overline{SS}$x/FSYNCx: Active-Low Slave Select or Frame Synchronization I/O Pulse

The SPIx module can be configured to operate with two, three or four pins. In 3-pin mode, $\overline{SS}$x is not used. In 2-pin mode, neither SDOx nor $\overline{SS}$x is used.

Figure 18-1 illustrates the block diagram of the SPIx module in Standard and Enhanced modes.

REGISTER 21-10: CxCFG2: ECANx BAUD RATE CONFIGURATION REGISTER 2

U-0	R/W-x	U-0	U-0	U-0	R/W-x	R/W-x	R/W-x
—	WAKFIL	—	—	—	SEG2PH2	SEG2PH1	SEG2PH0
bit 15							bit 8

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
SEG2PHTS	SAM	SEG1PH2	SEG1PH1	SEG1PH0	PRSEG2	PRSEG1	PRSEG0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as '0'

bit 14 **WAKFIL:** Select CAN Bus Line Filter for Wake-up bit
1 = Uses CAN bus line filter for wake-up
0 = CAN bus line filter is not used for wake-up

bit 13-11 **Unimplemented:** Read as '0'

bit 10-8 **SEG2PH<2:0>:** Phase Segment 2 bits
111 = Length is 8 x TQ
•
•
•
000 = Length is 1 x TQ

bit 7 **SEG2PHTS:** Phase Segment 2 Time Select bit
1 = Freely programmable
0 = Maximum of SEG1PHx bits or Information Processing Time (IPT), whichever is greater

bit 6 **SAM:** Sample of the CAN Bus Line bit
1 = Bus line is sampled three times at the sample point
0 = Bus line is sampled once at the sample point

bit 5-3 **SEG1PH<2:0>:** Phase Segment 1 bits
111 = Length is 8 x TQ
•
•
•
000 = Length is 1 x TQ

bit 2-0 **PRSEG<2:0>:** Propagation Time Segment bits
111 = Length is 8 x TQ
•
•
•
000 = Length is 1 x TQ

REGISTER 21-16: CxRXFnSID: ECANx ACCEPTANCE FILTER n STANDARD IDENTIFIER REGISTER (n = 0-15)

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
SID10	SID9	SID8	SID7	SID6	SID5	SID4	SID3
bit 15							bit 8

R/W-x	R/W-x	R/W-x	U-0	R/W-x	U-0	R/W-x	R/W-x
SID2	SID1	SID0	—	EXIDE	—	EID17	EID16
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-5 **SID<10:0>:** Standard Identifier bits
1 = Message address bit, SIDx, must be '1' to match filter
0 = Message address bit, SIDx, must be '0' to match filter

bit 4 **Unimplemented:** Read as '0'

bit 3 **EXIDE:** Extended Identifier Enable bit
If MIDE = 1:
1 = Matches only messages with Extended Identifier addresses
0 = Matches only messages with Standard Identifier addresses
If MIDE = 0:
Ignores EXIDE bit.

bit 2 **Unimplemented:** Read as '0'

bit 1-0 **EID<17:16>:** Extended Identifier bits
1 = Message address bit, EIDx, must be '1' to match filter
0 = Message address bit, EIDx, must be '0' to match filter

23.2 ADC Helpful Tips

1. The SMPIx control bits in the AD1CON2 register:
   a) Determine when the ADC interrupt flag is set and an interrupt is generated, if enabled.
   b) When the CSCNA bit in the AD1CON2 registers is set to '1', this determines when the ADC analog scan channel list, defined in the AD1CSSL/AD1CSSH registers, starts over from the beginning.
   c) When the DMA peripheral is not used (ADDMAEN = 0), this determines when the ADC Result Buffer Pointer to ADC1BUF0-ADC1BUFF gets reset back to the beginning at ADC1BUF0.
   d) When the DMA peripheral is used (ADDMAEN = 1), this determines when the DMA Address Pointer is incremented after a sample/conversion operation. ADC1BUF0 is the only ADC buffer used in this mode. The ADC Result Buffer Pointer to ADC1BUF0-ADC1BUFF gets reset back to the beginning at ADC1BUF0. The DMA address is incremented after completion of every 32nd sample/conversion operation. Conversion results are stored in the ADC1BUF0 register for transfer to RAM using DMA.
2. When the DMA module is disabled (ADDMAEN = 0), the ADC has 16 result buffers. ADC conversion results are stored sequentially in ADC1BUF0-ADC1BUFF, regardless of which analog inputs are being used subject to the SMPIx bits and the condition described in 1c) above. There is no relationship between the ANx input being measured and which ADC buffer (ADC1BUF0-ADC1BUFF) that the conversion results will be placed in.
3. When the DMA module is enabled (ADDMAEN = 1), the ADC module has only 1 ADC result buffer (i.e., ADC1BUF0) per ADC peripheral and the ADC conversion result must be read, either by the CPU or DMA Controller, before the next ADC conversion is complete to avoid overwriting the previous value.
4. The DONE bit (AD1CON1<0>) is only cleared at the start of each conversion and is set at the completion of the conversion, but remains set indefinitely, even through the next sample phase until the next conversion begins. If application code is monitoring the DONE bit in any kind of software loop, the user must consider this behavior because the CPU code execution is faster than the ADC. As a result, in Manual Sample mode, particularly where the user's code is setting the SAMP bit (AD1CON1<1>), the DONE bit should also be cleared by the user application just before setting the SAMP bit.
5. Enabling op amps, comparator inputs and external voltage references can limit the availability of analog inputs (ANx pins). For example, when Op Amp 2 is enabled, the pins for AN0, AN1 and AN2 are used by the op amp's inputs and output. This negates the usefulness of Alternate Input mode since the MUXA selections use AN0-AN2. Carefully study the ADC block diagram to determine the configuration that will best suit your application. Configuration examples are available in the **"Analog-to-Digital Converter (ADC)"** (DS70621) section in the "dsPIC33/PIC24 Family Reference Manual".

23.3 ADC Resources

Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note:	In the event you are not able to access the product page using the link above, enter this URL in your browser: http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en555464

23.3.1 KEY RESOURCES

- **"Analog-to-Digital Converter (ADC)"** (DS70621) in the "dsPIC33/PIC24 Family Reference Manual"
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All Related "dsPIC33/PIC24 Family Reference Manual" Sections
- Development Tools

REGISTER 23-4: AD1CON4: ADC1 CONTROL REGISTER 4

U-0	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0
—	—	—	—	—	—	—	ADDMAEN
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0
—	—	—	—	—	DMABL2	DMABL1	DMABL0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-9 **Unimplemented:** Read as ‘0’

bit 8 **ADDMAEN:** ADC1 DMA Enable bit

1 = Conversion results are stored in the ADC1BUF0 register for transfer to RAM using DMA
0 = Conversion results are stored in ADC1BUF0 through ADC1BUFF registers; DMA will not be used

bit 7-3 **Unimplemented:** Read as ‘0’

bit 2-0 **DMABL<2:0>:** Selects Number of DMA Buffer Locations per Analog Input bits

111 = Allocates 128 words of buffer to each analog input
110 = Allocates 64 words of buffer to each analog input
101 = Allocates 32 words of buffer to each analog input
100 = Allocates 16 words of buffer to each analog input
011 = Allocates 8 words of buffer to each analog input
010 = Allocates 4 words of buffer to each analog input
001 = Allocates 2 words of buffer to each analog input
000 = Allocates 1 word of buffer to each analog input

TABLE 27-1: CONFIGURATION BYTE REGISTER MAP

File Name	Address	Device Memory Size (Kbytes)	Bits 23-8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Reserved	0057EC	32	—	—	—	—	—	—	—	—	—
	00AFEC	64									
	0157EC	128									
	02AFEC	256									
	0557EC	512									
Reserved	0057EE	32	—	—	—	—	—	—	—	—	—
	00AFEE	64									
	0157EE	128									
	02AFEE	256									
	0557EE	512									
FICD	0057F0	32	—	Reserved(3)	—	JTAGEN	Reserved(2)	Reserved(3)	—	ICS<1:0>	
	00AFF0	64									
	0157F0	128									
	02AFF0	256									
	0557F0	512									
FPOR	0057F2	32	—	WDTWIN<1:0>		ALTI2C2	ALTI2C1	Reserved(3)	—	—	—
	00AFF2	64									
	0157F2	128									
	02AFF2	256									
	0557F2	512									
FWDT	0057F4	32	—	FWDTEN	WINDIS	PLLKEN	WDTPRE	WDTPOST<3:0>			
	00AFF4	64									
	0157F4	128									
	02AFF4	256									
	0557F4	512									
FOSC	0057F6	32	—	FCKSM<1:0>		IOL1WAY	—	—	OSCIOFNC	POSCMD<1:0>	
	00AFF6	64									
	0157F6	128									
	02AFF6	256									
	0557F6	512									
FOSCSEL	0057F8	32	—	IESO	PWMLOCK(1)	—	—	—	FNOSC<2:0>		
	00AFF8	64									
	0157F8	128									
	02AFF8	256									
	0557F8	512									
FGS	0057FA	32	—	—	—	—	—	—	—	GCP	GWRP
	00AFFA	64									
	0157FA	128									
	02AFFA	256									
	0557FA	512									
Reserved	0057FC	32	—	—	—	—	—	—	—	—	—
	00AFFC	64									
	0157FC	128									
	02AFFC	256									
	0557FC	512									
Reserved	057FFE	32	—	—	—	—	—	—	—	—	—
	00AFFE	64									
	0157FE	128									
	02AFFE	256									
	0557FE	512									

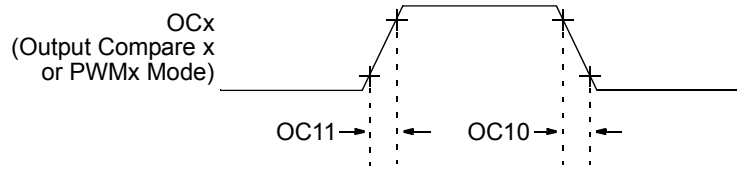
Legend: — = unimplemented, read as '1'.

Note 1: This bit is only available on dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices.

2: This bit is reserved and must be programmed as '0'.

3: These bits are reserved and must be programmed as '1'.

FIGURE 30-7: OUTPUT COMPARE x MODULE (OCx) TIMING CHARACTERISTICS



Note: Refer to Figure 30-1 for load conditions.

TABLE 30-27: OUTPUT COMPARE x MODULE TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
OC10	TccF	OCx Output Fall Time	—	—	—	ns	See Parameter DO32
OC11	TccR	OCx Output Rise Time	—	—	—	ns	See Parameter DO31

Note 1: These parameters are characterized but not tested in manufacturing.

FIGURE 30-8: OCx/PWMx MODULE TIMING CHARACTERISTICS

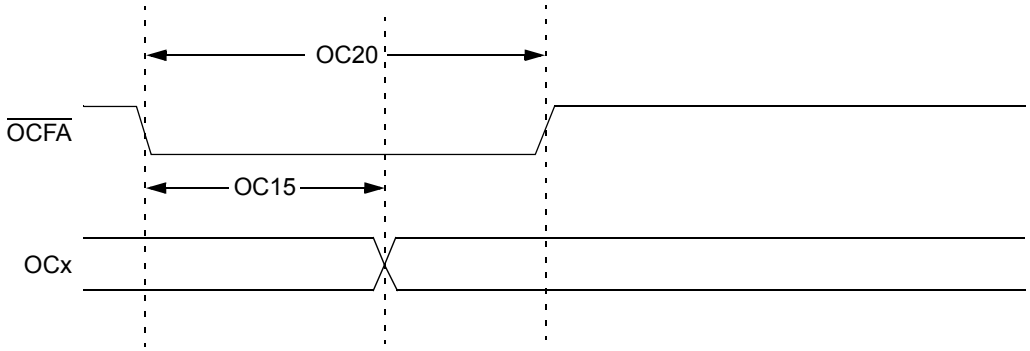


TABLE 30-28: OCx/PWMx MODE TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
OC15	TFD	Fault Input to PWMx I/O Change	—	—	TCY + 20	ns	
OC20	TFLT	Fault Input Pulse Width	TCY + 20	—	—	ns	

Note 1: These parameters are characterized but not tested in manufacturing.

TABLE 30-37: SPI2 SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 0, SMP = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
SP70	FscP	Maximum SCK2 Input Frequency	—	—	Lesser of FP or 15	MHz	**(Note 3)**
SP72	TscF	SCK2 Input Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP73	TscR	SCK2 Input Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP30	TdoF	SDO2 Data Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP31	TdoR	SDO2 Data Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP35	TscH2doV, TscL2doV	SDO2 Data Output Valid after SCK2 Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDO2 Data Output Setup to First SCK2 Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDI2 Data Input to SCK2 Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDI2 Data Input to SCK2 Edge	30	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{SS2}$ ↓ to SCK2 ↑ or SCK2 ↓ Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{SS2}$ ↑ to SDO2 Output High-Impedance	10	—	50	ns	**(Note 4)**
SP52	TscH2ssH TscL2ssH	$\overline{SS2}$ ↑ after SCK2 Edge	1.5 TCY + 40	—	—	ns	**(Note 4)**
SP60	TssL2doV	$\overline{SDO2}$ Data Output Valid after $\overline{SS2}$ Edge	—	—	50	ns	

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCK2 is 66.7 ns. Therefore, the SCK2 clock generated by the master must not violate this specification.

4: Assumes 50 pF load on all SPI2 pins.

TABLE 30-39: SPI2 SLAVE MO DE (FULL-DUPLEX, CKE = 0, CKP = 1, SMP = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C dTA d+85°C for Industrial -40°C dTA d+125°C for Extended				
Param.	Symbol	Characteristic (1)	Min.	Typ. (2)	Max.	Units	Conditions

TABLE 30-45: SPI1 SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 0, SMP = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
SP70	FscP	Maximum SCK1 Input Frequency	—	—	Lesser of FP or 15	MHz	**(Note 3)**
SP72	TscF	SCK1 Input Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP73	TscR	SCK1 Input Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP30	TdoF	SDO1 Data Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP31	TdoR	SDO1 Data Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP35	TscH2doV, TscL2doV	SDO1 Data Output Valid after SCK1 Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDO1 Data Output Setup to First SCK1 Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDI1 Data Input to SCK1 Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDI1 Data Input to SCK1 Edge	30	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{SS1}$ ↓ to SCK1 ↑ or SCK1 ↓ Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{SS1}$ ↑ to SDO1 Output High-Impedance	10	—	50	ns	**(Note 4)**
SP52	TscH2ssH TscL2ssH	$\overline{SS1}$ ↑ after SCK1 Edge	1.5 TCY + 40	—	—	ns	**(Note 4)**
SP60	TssL2doV	$\overline{SDO1}$ Data Output Valid after $\overline{SS1}$ Edge	—	—	50	ns	

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCK1 is 66.7 ns. Therefore, the SCK1 clock generated by the master must not violate this specification.

4: Assumes 50 pF load on all SPI1 pins.

Revision C (December 2011)

This revision includes typographical and formatting changes throughout the data sheet text.

In addition, where applicable, new sections were added to each peripheral chapter that provide information and links to related resources, as well as helpful tips. For examples, see **Section 20.1 "UART Helpful Tips"** and **Section 3.6 "CPU Resources"**.

All occurrences of TLA were updated to VTLA throughout the document, with the exception of the pin diagrams (updated diagrams were not available at time of publication).

A new chapter, **Section 31.0 "DC and AC Device Characteristics Graphs"**, was added.

All other major changes are referenced by their respective section in Table A-2.

TABLE A-2: MAJOR SECTION UPDATES

Section Name	Update Description
"16-bit Microcontrollers and Digital Signal Controllers (up to 256-Kbyte Flash and 32-Kbyte SRAM) with High-Speed PWM, Op amps, and Advanced Analog"	The content on the first page of this section was extensively reworked to provide the reader with the key features and functionality of this device family in an "at-a-glance" format.
Section 1.0 "Device Overview"	Updated the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X, and PIC24EPXXXGP/MC20X Block Diagram (see Figure 1-1), which now contains a CPU block and a reference to the CPU diagram. Updated the description and Note references in the Pinout I/O Descriptions for these pins: C1IN2-, C2IN2-, C3IN2-, OA1OUT, OA2OUT, and OA3OUT (see Table 1-1).
Section 2.0 "Guidelines for Getting Started with 16-bit Digital Signal Controllers and Microcontrollers"	Updated the Recommended Minimum Connection diagram (see Figure 2-1).
Section 3.0 "CPU"	Updated the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X, and PIC24EPXXXGP/MC20X CPU Block Diagram (see Figure 3-1). Updated the Status register definition in the Programmer's Model (see Figure 3-2).
Section 4.0 "Memory Organization"	Updated the Data Memory Maps (see Figure 4-6 and Figure 4-11). Removed the DCB<1:0> bits from the OC1CON2, OC2CON2, OC3CON2, and OC4CON2 registers in the Output Compare 1 Through Output Compare 4 Register Map (see Table 4-10). Added the TRIG1 and TRGCON1 registers to the PWM Generator 1 Register Map (see Table 4-13). Added the TRIG2 and TRGCON2 registers to the PWM Generator 2 Register Map (see Table 4-14). Added the TRIG3 and TRGCON3 registers to the PWM Generator 3 Register Map (see Table 4-15). Updated the second note in **Section 4.7.1 "Bit-Reversed Addressing Implementation"**.
Section 8.0 "Direct Memory Access (DMA)"	Updated the DMA Controller diagram (see Figure 8-1).
Section 14.0 "Input Capture"	Updated the bit values for the ICx clock source of the ICTSEL<12:10> bits in the ICxCON1 register (see Register 14-1).
Section 15.0 "Output Compare"	Updated the bit values for the OCx clock source of the OCTSEL<2:0> bits in the OCxCON1 register (see Register 15-1). Removed the DCB<1:0> bits from the Output Compare x Control Register 2 (see Register 15-2).

Revision H (August 2013)

This revision includes minor typographical and formatting changes throughout the text.

Other major changes are referenced by their respective section in Table A-6.

TABLE A-6: MAJOR SECTION UPDATES

Section Name	Update Description
Cover Section	• Adds Peripheral Pin Select (PPS) to allow Digital Function Remapping and Change Notification Interrupts to Input/Output section • Adds heading information to 64-Pin TQFP
Section 4.0 "Memory Organization"	• Corrects Reset values for ANSELE, TRISF, TRISC, ANSELC and TRISA • Corrects address range from 0x2FFF to 0x7FFF • Corrects DSRPAG and DSWPAG (now 3 hex digits) • Changes Call Stack Frame from <15:1> to PC<15:0> • Word length in Figure 4-20 is changed to 50 words for clarity
Section 5.0 "Flash Program Memory"	• Corrects descriptions of NVM registers
Section 9.0 "Oscillator Configuration"	• Removes resistor from Figure 9-1 • Adds Fast RC Oscillator with Divide-by-16 (FRCDIV16) row to Table 9-1 • Removes incorrect information from ROI bit in Register 9-2
Section 14.0 "Input Capture"	• Changes 31 user-selectable Trigger/Sync interrupts to 19 user-selectable Trigger/Sync interrupts • Corrects ICTSEL<12:10> bits (now ICTSEL<2:0>)
Section 17.0 "Quadrature Encoder Interface (QEI) Module (dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X Devices Only)"	• Corrects QCAPEN bit description
Section 19.0 "Inter-Integrated Circuit™ (I^2C™)"	• Adds note to clarify that 100kbit/sec operation of I^2C is not possible at high processor speeds
Section 22.0 "Charge Time Measurement Unit (CTMU)"	• Clarifies Figure 22-1 to accurately reflect peripheral behavior
Section 23.0 "10-Bit/12-Bit Analog-to-Digital Converter (ADC)"	• Correct Figure 23-1 (changes CH123x to CH123Sx)
Section 24.0 "Peripheral Trigger Generator (PTG) Module"	• Adds footnote to Register 24-1 (In order to operate with CVRSS=1, at least one of the comparator modules must be enabled.
Section 25.0 "Op Amp/ Comparator Module"	• Adds note to Figure 25-3 (In order to operate with CVRSS=1, at least one of the comparator modules must be enabled) • Adds footnote to Register 25-2 (COE is not available when OPMODE (CMxCON<10>) = 1)
Section 27.0 "Special Features"	• Corrects the bit description for FNOSC<2:0>
Section 30.0 "Electrical Characteristics"	• Corrects 512K part power-down currents based on test data • Corrects WDT timing limits based on LPRC oscillator tolerance
Section 31.0 "High-Temperature Electrical Characteristics"	• Adds Table 31-5 (DC Characteristics: Idle Current (I_{IDLE})